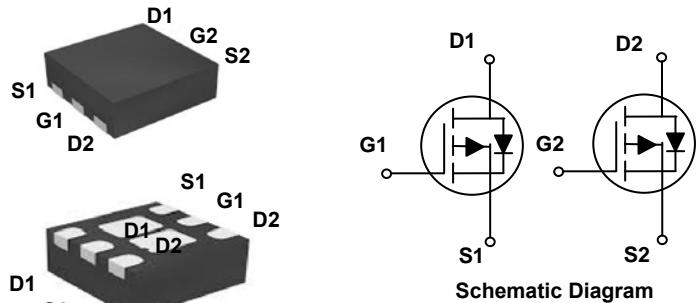


Main Product Characteristics

BV _{DSS}	-30V
R _{DS(ON)}	65mΩ (typ)
I _D	-4.2A



Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery

Description

The GSFB0305 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supply and a wide variety of other applications.

Absolute Maximum Ratings (T_C=25°C unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V _{DS}	-30	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous (T _A =25°C)	I _D	-4.2	A
Drain Current-Continuous (T _A =70°C)		-3.4	
Drain Current-Continuous (T _c =25°C)		-8	
Drain Current-Continuous (T _c =100°C)		-5.1	
Drain Current-Pulsed ¹	I _{DM}	-16.8	A
Power Dissipation (T _A =25°C)	P _D	1.9	W
Power Dissipation (T _c =25°C)		7.4	W/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA}	65	°C/W
Thermal Resistance, Junction-to-Case	R _{θJC}	17	°C/W
Operating Junction Temperature Range	T _J	-55 To +150	°C
Storage Temperature Range	T _{STG}	-55 To +150	°C



Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On/Off Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30	-	-	V
BV_{DSS} Temperature Coefficient	$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	Reference to 25°C , $I_{\text{D}}=-1\text{mA}$	-	-0.03	-	$\text{V}/^\circ\text{C}$
Drain-Source Leakage Current	$I_{\text{DS}(\text{SS})}$	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	-	-	-1	μA
		$V_{\text{DS}}=-24\text{V}, V_{\text{GS}}=0\text{V}, T_J=125^\circ\text{C}$	-	-	-10	μA
Gate-Source Leakage Current	I_{GSS}	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-3\text{A}$	-	64	75	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-1.5\text{A}$	-	105	130	
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=-250\mu\text{A}$	-1.2	-1.6	-2.5	V
$V_{\text{GS}(\text{th})}$ Temperature Coefficient	$\Delta V_{\text{GS}(\text{th})}$		-	4	-	$\text{mV}/^\circ\text{C}$
Forward Transconductance	g_{fs}	$V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-3\text{A}$	-	4	-	S
Dynamic and Switching Characteristics						
Total Gate Charge ^{2,3}	Q_g	$V_{\text{DS}}=-15\text{V}, I_{\text{D}}=-2\text{A}$ $V_{\text{GS}}=-4.5\text{V}$	-	5	10	nC
Gate-Source Charge ^{2,3}	Q_{gs}		-	1.4	3	
Gate-Drain Charge ^{2,3}	Q_{gd}		-	1.7	4	
Turn-On Delay Time ^{2,3}	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=-15\text{V}, R_{\text{G}}=25\Omega$ $V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-1\text{A}$	-	3.4	8	nS
Rise Time ^{2,3}	t_r		-	12	24	
Turn-Off Delay Time ^{2,3}	$t_{\text{d}(\text{off})}$		-	16	32	
Fall Time ^{2,3}	t_f		-	7	14	
Input Capacitance	C_{iss}	$V_{\text{DS}}=-15\text{V}, V_{\text{GS}}=0\text{V}, F=1\text{MHz}$	-	420	820	pF
Output Capacitance	C_{oss}		-	50	100	
Reverse Transfer Capacitance	C_{rss}		-	35	70	
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I_s	$V_G=V_D=0\text{V},$ Force Current	-	-	-4	A
Pulsed Source Current ³	I_{SM}		-	-	-8	A
Diode Forward Voltage ³	V_{SD}	$V_{\text{GS}}=0\text{V}, I_s=-1\text{A}, T_J=25^\circ\text{C}$	-	-	-1	V

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2. Pulse tested: pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
3. Essentially independent of operating temperature.

Typical Electrical and Thermal Characteristic Curves

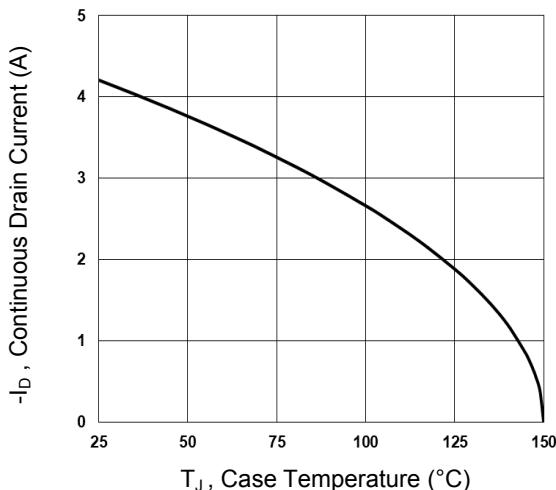


Figure 1. Continuous Drain Current vs. T_J

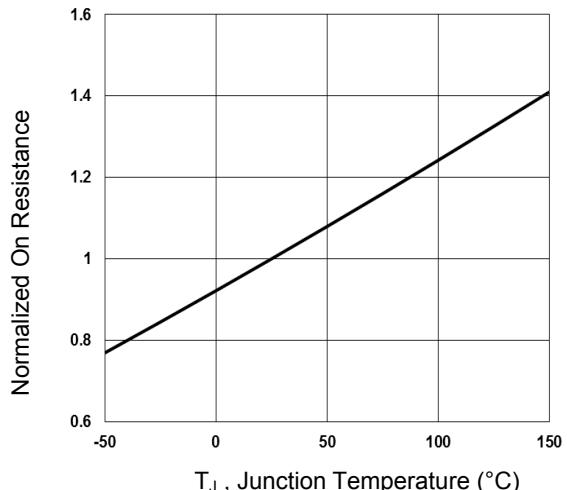


Figure 2. Normalized R_{DS(ON)} vs. T_J

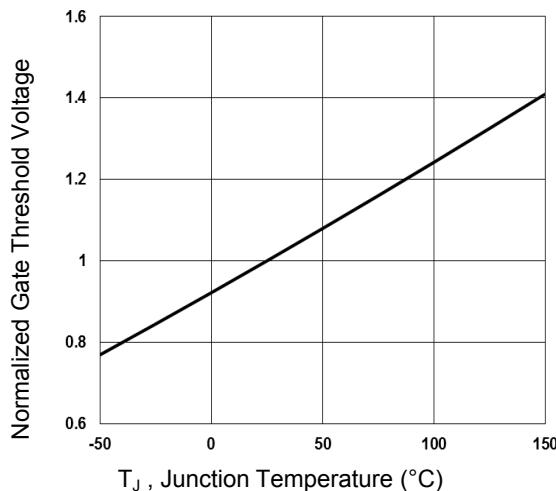


Figure 3. Normalized V_{th} vs. T_J

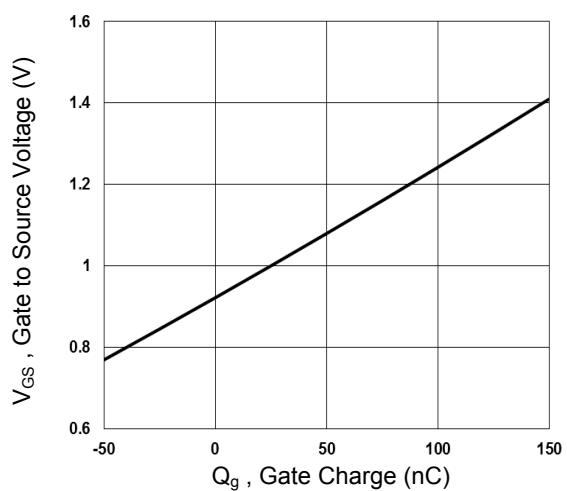


Figure 4. Gate Charge Waveform

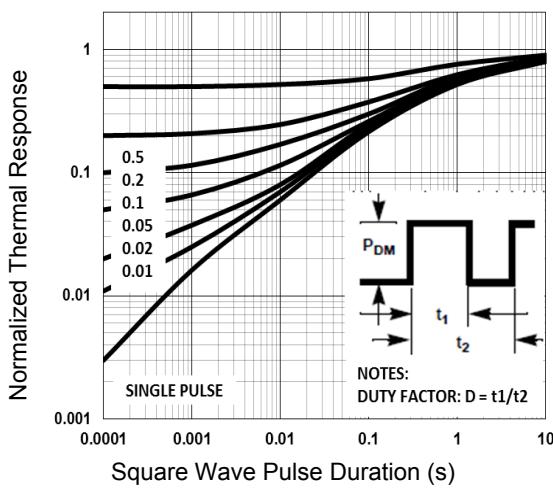


Figure 5. Normalized Transient Response

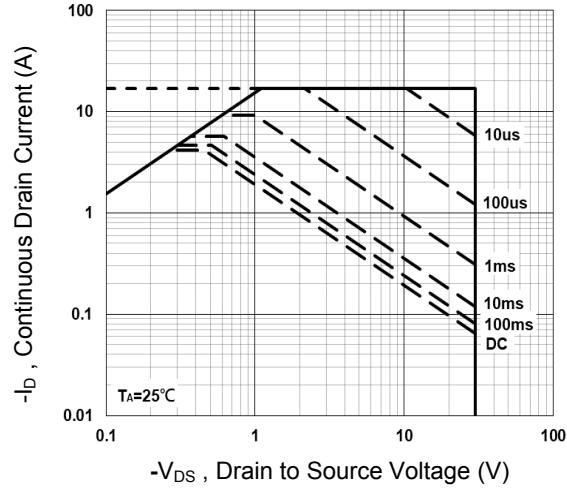


Figure 6. Maximum Safe Operation Area

Typical Electrical and Thermal Characteristic Curves

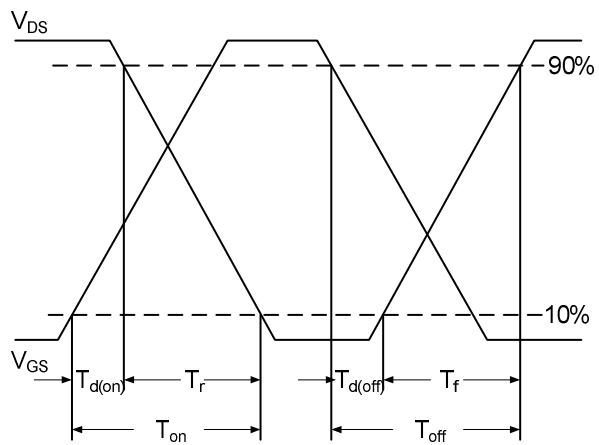


Figure 7. Switching Time Waveform

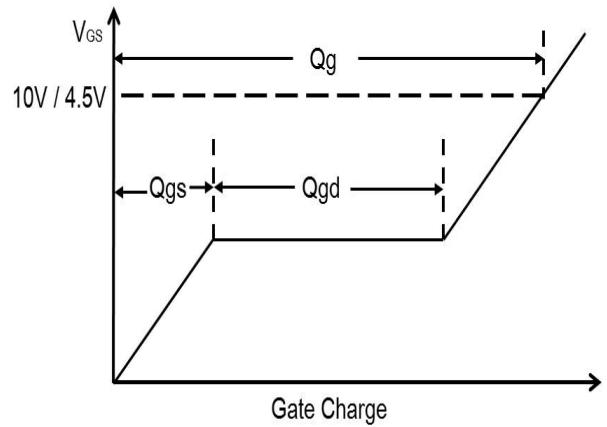
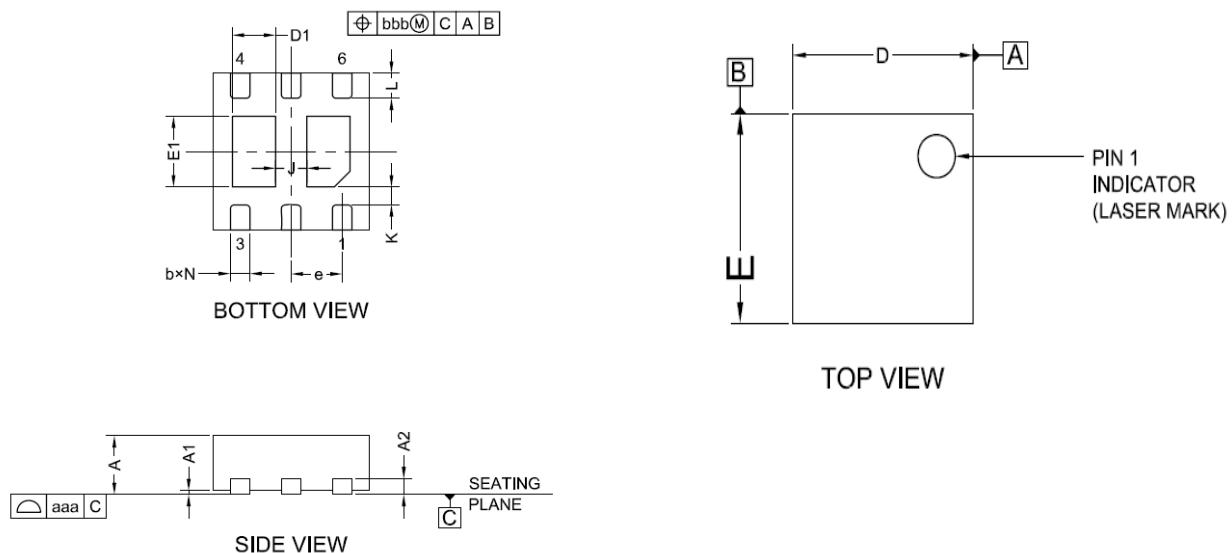


Figure 8. Gate Charge Waveform

Package Outline Dimensions (PPAK 2x2 Duel 2EP)



COMMON DIMENSIONS

(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	TYP	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A2		0.203	
b	0.20	0.25	0.30
D	1.95	2.00	2.05
D1	0.50	0.55	0.60
E	1.95	2.00	2.05
E1	0.85	0.90	0.95
e		0.65BSC	
L	0.27	0.32	0.37
J		0.40BSC	
K		0.20MIN	
N		6	
aaa		0.08	
bbb		0.10	

Recommended Pad Layout

